

BB02-CU :- 1.27mm X 1.27mm SOCKET, DUAL ROW, STRAIGHT, THROUGH HOLE, 6 to 100 CONTACTS

SPECIFICATIONS

CURRENT RATING	1 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
CONTACTS RESISTANCE	20m OHMS MAX.
DIELECTRIC WITHSTANDING	AC 300 V
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	POLYESTER UL 94V-0
	STANDARD: NYLON 6T

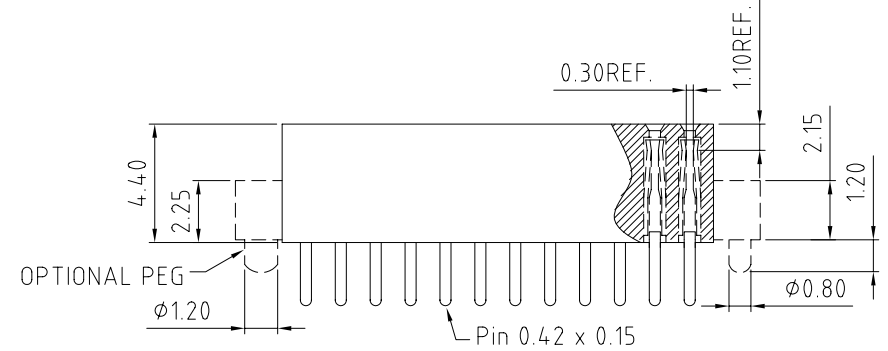
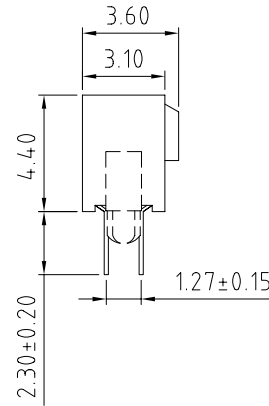
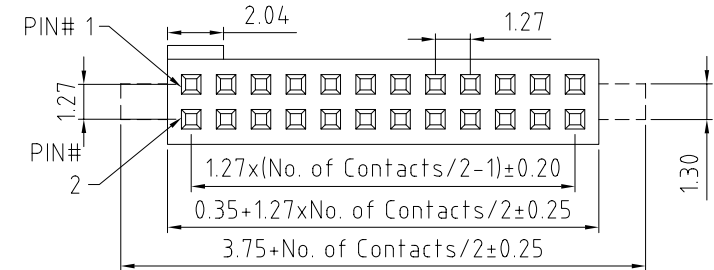
PLATING GOLD, TIN, OR SELECTIVE OVER 30~50U" NICKEL
 SOLDERABILITY: IR REFLOW: 260°C FOR 10 SEC
 WAVE: 230°C FOR 5-10 SEC
 MANUAL SOLDER: 350°C FOR 3-5 SEC

NOTES:

1. RECOMMENDED MATING PIN LENGTH : 3.0MM

MATES WITH:-

BB02-BC	BB02-BS
BB02-BD	BB02-BY
BB02-BE	BB02-BZ
BB02-BK	BB02-NE
BB02-BP	



HOW TO ORDER

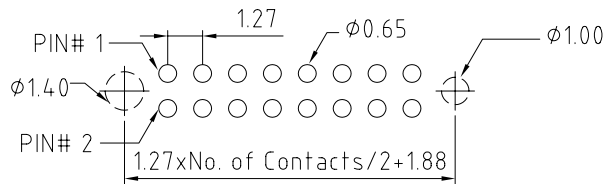


NO. OF CONTACTS
 06 TO 98
 00 = 100

CONTACT PLATING OPTIONS
 K = GOLD FLASH (STANDARD)
 A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 T = BRIGHT TIN
 M = MATT TIN
 D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL
 E = 10U" GOLD ON CONTACT/BRIGHT TIN ON TAIL
 F = 15U" GOLD ON CONTACT/BRIGHT TIN ON TAIL
 G = 30U" GOLD ON CONTACT/BRIGHT TIN ON TAIL

PACKING OPTIONS
 3 = TUBE
 4 = TUBE & FILM
 5 = TUBE & CAP
 6 = T+R
 7 = T+R+FILM
 8 = T+R+CAP

WITH OR WITHOUT LOCATING PEG
 A = WITH PEG
 B = WITHOUT PEG



RECOMMENDED PC BOARD HOLED LAYOUT

REV.	DATE & DRN
10	28/07/05 - NTW - RELEASE
11	20/07/06 - NYW - DRAWING MODIFICATION
12	05/06/07 - CHC - ADD NOTES 1
13	21/05/08 - CHC - PLATING MODIFICATION
14	14/08/08 - NYW - ADD PIN 1 INDICATION
15	26/12/08 - CHC - DRAWING MODIFICATION

Scale: 5:1	THIRD ANGLE	Unstated Tolerances: X ± 0.30 XX ± 0.25 XXX ± 0.15 XXX ± 0.10	Material: SEE NOTE
Drawn: CHC	Title: SOCKET		NOT TO SCALE
App'd: XXXX	Revision: 15		UNIT: mm
Date: 26 DEC '08			



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Type: BB02-CU
BB02-CU
DRAWING NUMBER:
Sheet 1 of 1
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